CLAIMS

1. A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m characterized in that a skewness (deflection) "Rsk" of the zirconia surface layer is from –0.5 to 0.5.

2. A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m, characterized in that a skewness (deflection) "Rsk" of the zirconia surface layer is from –0.5 to 0.5.

3. The jig for calcining the electronic component as claimed in claim 1 or 2, wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

characterized in that a wear resistance in a reciprocating wear test conducted in accordance with JIS-H8503 is from 10 to 200 (DS/mg).

12. The jig for calcining the electronic component as claimed in claim 10 or 11, wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μm bonded with each other by a sintering aid made of two or more metal oxides for increasing the wear resistance.

13. A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate, characterized in that a thermal shock resistance ΔT (=T1-T2) is 400℃ or more expressed as a temperature difference of rapid cooling which generates strength reduction in a rapid cooling bending test where the jig for calcining the electronic component is rapidly cooled from specified temperature T1 to T2.

14. A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia layer formed on the intermediate layer, characterized in that a thermal shock resistance ΔT is 400℃ or more.

15. The jig for calcining the electronic component as claimed in claim 13, wherein a thickness of the zirconia layer formed on the substrate is 500μm or less, and a relative density of the zirconia surface layer is between 40 % and 80% both inclusive.

16. The jig for calcining the electronic component as claimed in claim 14, wherein a total thickness of the zirconia layer formed on the alumina intermediate layer (alumina intermediate layer + zirconia layer) is 500μm or less; a relative density of the zirconia layer is between 40 % and 80% both inclusive; and a relative density of the alumina intermediate layer is between 60 % and 90% both inclusive.

17. The jig for calcining the electronic component as claimed in claim 13 or 14, wherein metal oxides are used as a sintering aid for calcining the zirconia layer coated on the substrate surface, alumina intermediate layer coated on the substrate surface, and the zirconia layer coated on the alumina intermediate layer.